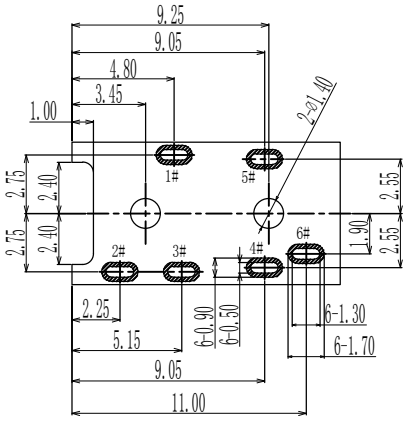
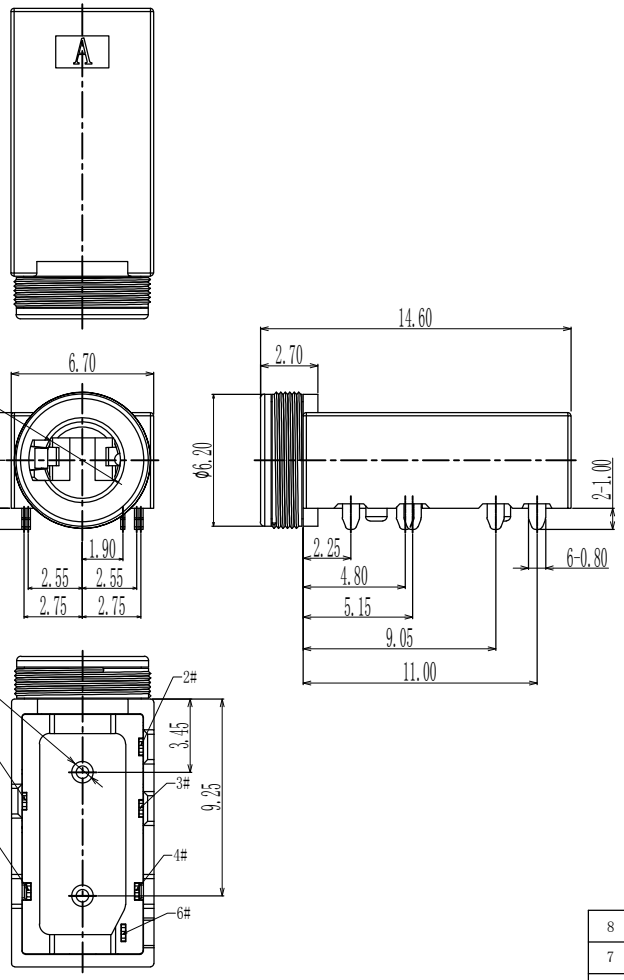
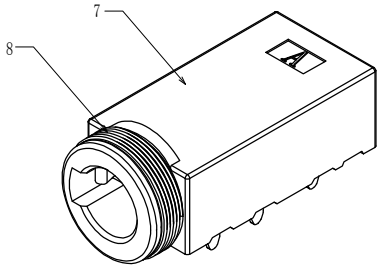
RoHS Compliant



P.C.B LAYOU T=1.00mm

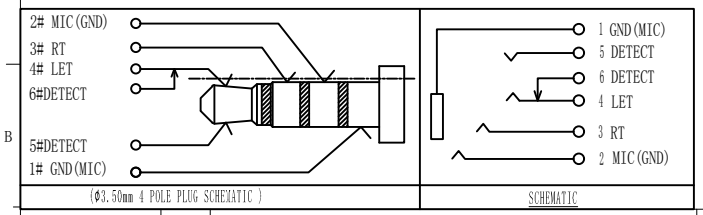
TOP VIEW





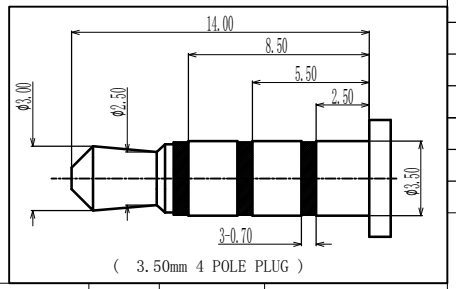
3D VIEW

1. CONTACT CURRENT RATING: 1A.
2. CONTACT RESISTANCE: 100 mΩ MAX.;
3. INSULATION RESISTANCE: 100MΩ MIN.;
4. DIELECTRIC WITHSTANDING: 500V AC MIN.;
5. DURABILITY: 5,000 CYCLES MIN.;
6. CONNECTOR MATING FORCES: 30N MAX.;
7. CONNECTOR UNMATING FORCES: 3N MIN.;
8. TERPROOF LEVEL: IP67;



(Ø3.50mm 4 POLE PLUG SCHEXATIC)

SCHEMATIC



(3.50mm 4 POLE PLUG)

NO.	DESCRIPTION	MATERIAL	QTY
8	WATERPROOF RING	SILICA GEL	
7	HOUSING	HIGH TEMPERATURE PLASTIC MATERIALE; COLOR BLACK	
6	TERMINAL 6#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL,GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm
5	TERMINAL 5#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL,GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm
4	TERMINAL 4#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL,GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm
3	TERMINAL 3#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL,GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm
2	TERMINAL 2#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL,GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm
1	TERMINAL 1#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL,GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm

ECN NO.	REV.	DESCRIPTION	DATE	CHANGE
N/A	A	NEW DRAWING	2019.10.06	Liu Miao

DESIGN	Liu Miao	2019.10.06
CHECK	SIMON	2019.10.06
APPROVAL	DAVID	2019.10.06

UNLESS OTHERWISE, GENERAL TOLERANCE:

X.xxx	±0.10
X.xx	±0.20
X.x	±0.30
X.	±0.50

ANGULAR:

X.xx	±1°
X.x	±3°
X.	±5°

WFDCONN 深圳市旺富达电子有限公司
Shenzhen WFD Electronics Co.Ltd..

TITLE: Ø3.5 WATERPROOF PHONE JACK CONNECTOR
客户图

P/N: MPJ-06C36-06-G-019

MODEL:

DRAW NO.:

THIRD ANGLE PROJECTION	UNIT:	SCALE:	SIZE:	SHEET:
	mm	1:1	A4	1/1